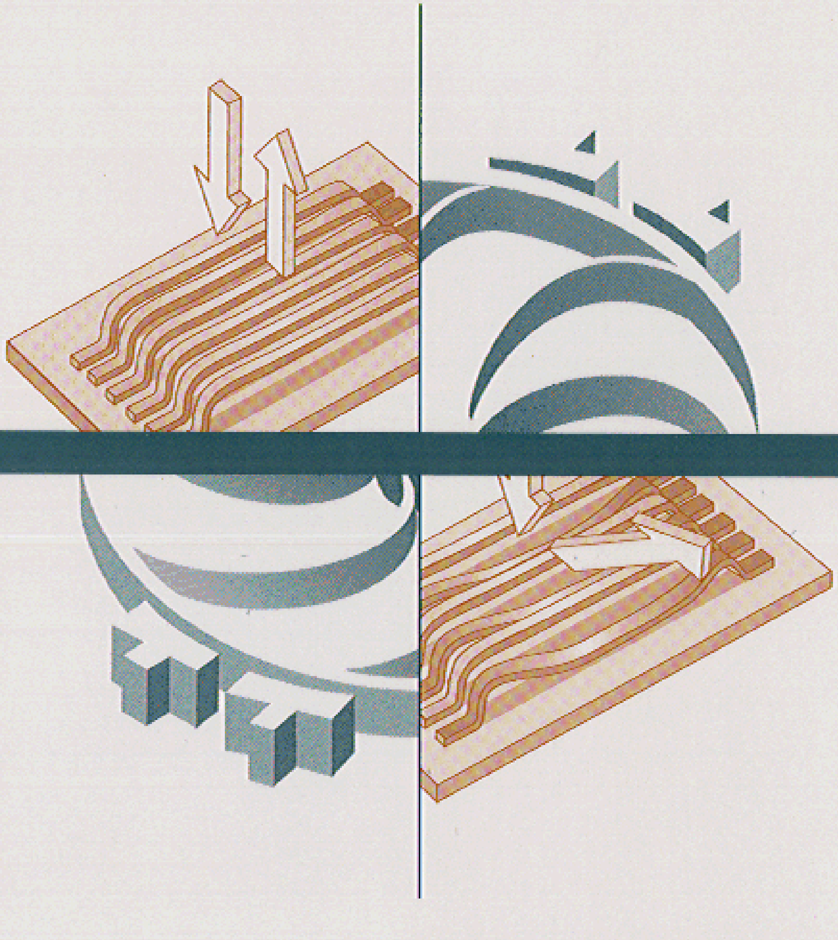
MEMS

MICROELECTROMECHANICAL SYSTEMS SERIES

An Introduction to Microelectromechanical Systems Engineering

SECOND EDITION



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